JUL 2 6 2004 E

DJT/DLW/ets

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Premakaran T. Boaz and John Pereira

Application No.:

10/802,387

Group: 1742

Filed:

March 17, 2004

Examiner: Not Assigned

Confirmation No.:

3670

This Information Disclosure Statement is submitted:

For:

SOLDER COMPOSITION

CERTIFICATE OF MAILING OR TRANSMISSION I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as First Class Mail in an envelope addressed to Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, or is being facsimile transmitted to the United States Patent and Trademark Office on: O7/22/04 Date Signature Ellen T. Soear Typed or printed name of person signing certificate

INFORMATION DISCLOSURE STATEMENT

Mail Stop Amendment Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Sir:

[]	under 37 CFR 1.129(a), or (First/Second submission after Final Rejection)
[]	X]	under 37 CFR 1.97(b), or (Within any one of the following time periods: three months of filing national application (other than a CPA) or date of entry of the national stage in an international application; or before the mailing date of a first office action on the merits in a non-provisional application, including a CPA, or a Request for Continued Examination).
[]	under 37 CFR 1.97(c) together with either:
		[] a Statement under 37 CFR 1.97(e), as checked below, or
		[] a \$180.00 fee under 37 CFR 1.17(p), or (After the 37 CFR 1.97(b) time period, but before final action or notice of allowance, whichever occurs first)
[]	under 37 CFR 1.97(d) together with:
		[] a Statement under 37 CFR 1.97(e), as checked below, and
		[] a \$180.00 fee under 37 CFR 1.17(p), or (Filed after final action or notice of allowance, whichever occurs first, but on or before payment of the issue fee)
[]	under 37 CFR 1.97(i): Applicant requests that the IDS and cited reference(s) be placed in the application filewrapper. (Filed after payment of issue fee)

Staten	ient On	der 37 C	<u> </u>				
	any co	mmunio	nformation contained in this Information Disclosure Statement was first cited in cation from a foreign patent office in a counterpart foreign application not more on the filing of this Information Disclosure Statement; or				
[]	No item of information contained in this Information Disclosure Statement was cited in a communication from a foreign patent office in a counterpart foreign application, and, to the knowledge of the undersigned, after making reasonable inquiry, no item of information contained in the information disclosure statement was known to any individual designated in 37 CFR 1.56(c) more than three months prior to the filing of this Information Disclosure Statement.						
Staten	nent Un	der 37 ((Patent Term Adjustment) Applies to original applications (other than design) filed on or after May 29, 2000				
[]	comm was no	unication ot receiv	information contained in the Information Disclosure Statement was cited in a confrom a foreign patent office in a counterpart application and this communication red by any individual designated in § 1.56(c) more than thirty days prior to the aformation Disclosure Statement.				
[X]	Enclos	sed here	with is form PTO-1449:				
	[X]	s of the cited references are enclosed.					
		[X]	Since this application was filed after June 30, 2003, copies of issued U.S. patents and published U.S. applications are not required and are not being provided.				
	[]	Applic	s of the cited references are enclosed except those entered in prior application, U.S. eation No. [], to which priority under 35 U.S.C. 120 is claimed. [The earlier ation contains copies of the cited references.]				
	[]	The list	sted references were cited in the enclosed International Search Report in a rpart foreign application.				
	[]	The "cunder"	oncise explanation" requirement (non-English references) for reference(s) [37 CFR 1.98(a)(3) is satisfied by:				
		[]	the explanation provided on the attached sheet.				
		[]	the explanation provided in the Specification.				
		[]	submission of the enclosed International Search Report.				
		[]	submission of the enclosed English-language version of a foreign Search Report and/or foreign Office Action.				
		[]	the enclosed English language abstract.				

[]	Applic	ant requests that the following n	on-published pending applic	cations be considered:	
Examiner's Initials					
		U.S. Patent Application No. [], by [inventor(s)], filed [], Docket No.: []	
		U.S. Patent Application No. [], by [inventor(s)], filed [], Docket No.: []	
		U.S. Patent Application No. [], by [inventor(s)], filed [], Docket No.: []	
		Examiner	Date	_	
	[]	A copy of each above-cited app	olication, including the curre	nt claims, is enclosed.	
	[]	A copy of each above-cited app those entered in prior application 35 U.S.C. 120 is claimed.			
The Ex	kaminei	is requested to return a copy of re considered with the next offic	the above list of pending ap e communication.	plications indicating which	
It is re	quested	that the information disclosed h	erein be made of record in the	his application.	
Metho	d of pay	yment:			
[]	A checaccom	ck for the fee noted above is encl panying Reply. A copy of this S	losed, or the fee has been incotatement is enclosed.	cluded in the check with the	
[]	Please enclos	charge Deposit Account 08-0380 in the amount of \$[]. A copy of this Statement is ed.			
[X]	Please charge any deficiency in fees and credit any overpayment to Deposit Account 08-0380.				
		F	Respectfully submitted,	•	
			Darrell L. Wong Registration No.: 36,725 Telephone: (978) 341-0036 Facsimile: (978) 341-0136	<u>)</u>	

Concord, MA 01742-9133 Dated: 7/72/2004

PTO-1449 REPRODUCED	ATTORNEY DOCKET NO. 2678.2011-000	APPLICATION NO. 10/802,387		
P ENFORMATION DISCLOSURE CITATION IN AN APPLICATION			FILING DATE March 17, 2004	
July 20, 2004 July 20, 2004 July 20, 2004	EXAMINER not assigned		IRMATION NO. Assigned	GROUP not assigned

PA.	-40							
U.S. PATENT DOCUMENTS								
EXAM- INER INI- TIAL	REF. NO.	DOCUMENT NUMBER Number-Kind Code (if known)	ISSUE DATE / PUBLICATION DATE MM-DD-YYYY	NAME OF PATENTEE OR APPLICANT OF CITED DOCUMENT				
	AA	5,066,544	11/19/1991	Betrabet et al.				
	AB	5,384,090	01/24/1995	Ogashiwa				
	AC	5,918,795	07/06/1999	Yamaguchi et al.				
	AD	US 6,253,988 B1	07/03/2001	Pereira				
	AE	US 6,319,461 B1	11/20/2001	Domi et al.				
	AF	US 6,371,361 B1	04/16/2002	Yamaguchi et al.				
	AG							
	АН							
	AI							
	AJ							
	AK							
	AA2							
	AB2							
	AC2							
	AD2							
	AE2							
	AF2							
	AG2							
	AH2							
	AI2							
	AJ2			,				
	AK2							
	AA3							
	AB3							
	AC3							

EXAMINER	DATE CONSIDERED

PTO-1449 REPRODUCED			PLICATION NO. /802,387		
INFORMATION DISCLOSURE CITATION IN AN APPLICATION	FIRST NAMED INVENTOR Premakaran T. Boaz		FILING DATE March 17, 2004		
July 20, 2004 (Use several sheets if necessary)	EXAMINER not assigned		IRMATION NO.	GROUP not assigned	

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)					
AR	Lee, NC., "Getting Ready for Lead-free Solders," Soldering & Surface Mount Technology, 26: 64-69 (July 1997).				
AS	Hwang, J.S., "Lead-free Solders," Modern Solder Technology for Competitive Electronics Manufacturing, Chapter 15: pp. 483-509, McGraw-Hill (1996).				
AT	Beal, RE. and Bader, W.G., "Soldering," Chapter in book, Edited by O'Brien, R.L., Welding Handbook, vol. 2, Chapter 13: pp. 423-447 (1991).				
AU					
AV					
AW					
AX					
AY					
AZ					
AR2					
AS2					
AT2					
AU2					
AV2	/				
AW2					
AX2					

EXAMINER	DATE CONSIDERED	
	I	